TECHNICAL DATA SHEET

HS-2210

Inorganic High-Temperature Adhesive

Two-part, heat-cured adhesive for bonding, sealing, filling and repair in dry high-temperature environments. Part A is a liquid and Part B is a powder. The cured material is a hard, grey-white solid.

Product data

Property	Supplied specification
Appearance	Part A: grey-white viscous liquid Part B: white powder
Continuous service temperature	-40 to +1000 °C, dry service
Short-term peak temperature	Up to +1200 °C; validate for the application
Mix ratio by weight, A:B	10:10 for bonding 10:17-20 for potting, filling and sealing
Working time	Use mixed material within 4 hours
Tensile shear strength	≥1.5 MPa after curing at 100 °C for 2 hours
Pressure resistance*	≥5.0 MPa after curing at 100 °C for 2 hours
Pack sizes	1.6 kg/set or 12 kg/set
Storage	At or below 28 °C; relative humidity at or below 70%
Shelf life	12 months, unopened in original packaging under specified storage conditions

*The source describes this property as pressure resistance; the test method and specimen geometry are not specified. Strength values are supplied ratings, not independently verified test results.

Suitable applications

Bonding and sealing of ceramics, quartz, metals, stainless steel and refractory materials. Typical uses include heater components, probes and sensors, furnace and kiln parts, and high-temperature housing or pipe repairs. Confirm suitability with application trials.

1. Prepare and mix

Clean and dry all bonding surfaces. Remove oil, dust and loose oxide. Weigh Part A and Part B using the ratio appropriate to the application. Mix thoroughly into a uniform paste without lumps. Use within 4 hours; discard mixed material that has formed lumps or dried.

2. Apply

Apply by brush, spatula, dispensing or filling. Fully fill the joint or repair area and press the material into gaps. Remove excess uncured adhesive from tools with water.

3. Cure - select the appropriate process

Recommended staged cure

Use for potting, thick deposits and demanding applications. Heat gradually, then allow the assembly to cool with the oven.

Stage	Temperature	Hold time
1	Room temperature	2 hours
2	40 °C	1.5-2 hours
3	60-70 °C	1-2 hours
4	110 °C	4-6 hours
5	Cool with the oven	To room temperature

Simplified cure

For ordinary bonding and sleeve joints with gaps below 0.2 mm: heat gradually to 100 °C, hold for 2 hours, then cool with the oven. Do not apply this short schedule to thick potting sections without validation.

Room-temperature cure at 20 °C takes approximately 5-7 days and produces lower strength; it is not recommended as the sole cure process. Avoid sudden high-temperature heating.

Handling and storage notes

Keep unmixed components and cured parts dry. The cured material can absorb moisture, reducing electrical insulation performance. This product is intended for dry service and is not suitable for prolonged water immersion. Store sealed, away from heat and direct sunlight, in a cool, dry, ventilated area. Request the current safety data sheet (SDS) for handling and protective equipment guidance.

Prepared from the supplied HS-2210 product specification. Performance depends on substrates, joint design, mix ratio, cure and service conditions. Validate the complete process before production use.